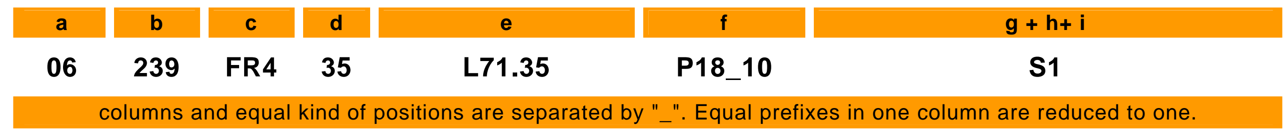
PRINTED CIRCUIT BOARDS

INTERCONNECTION CARRIERS

State of the Art: PCB's

PRINTED CIRCUIT BOARDS	Revisio	Datum:	Seite:
	01	4.11.2001	1/1

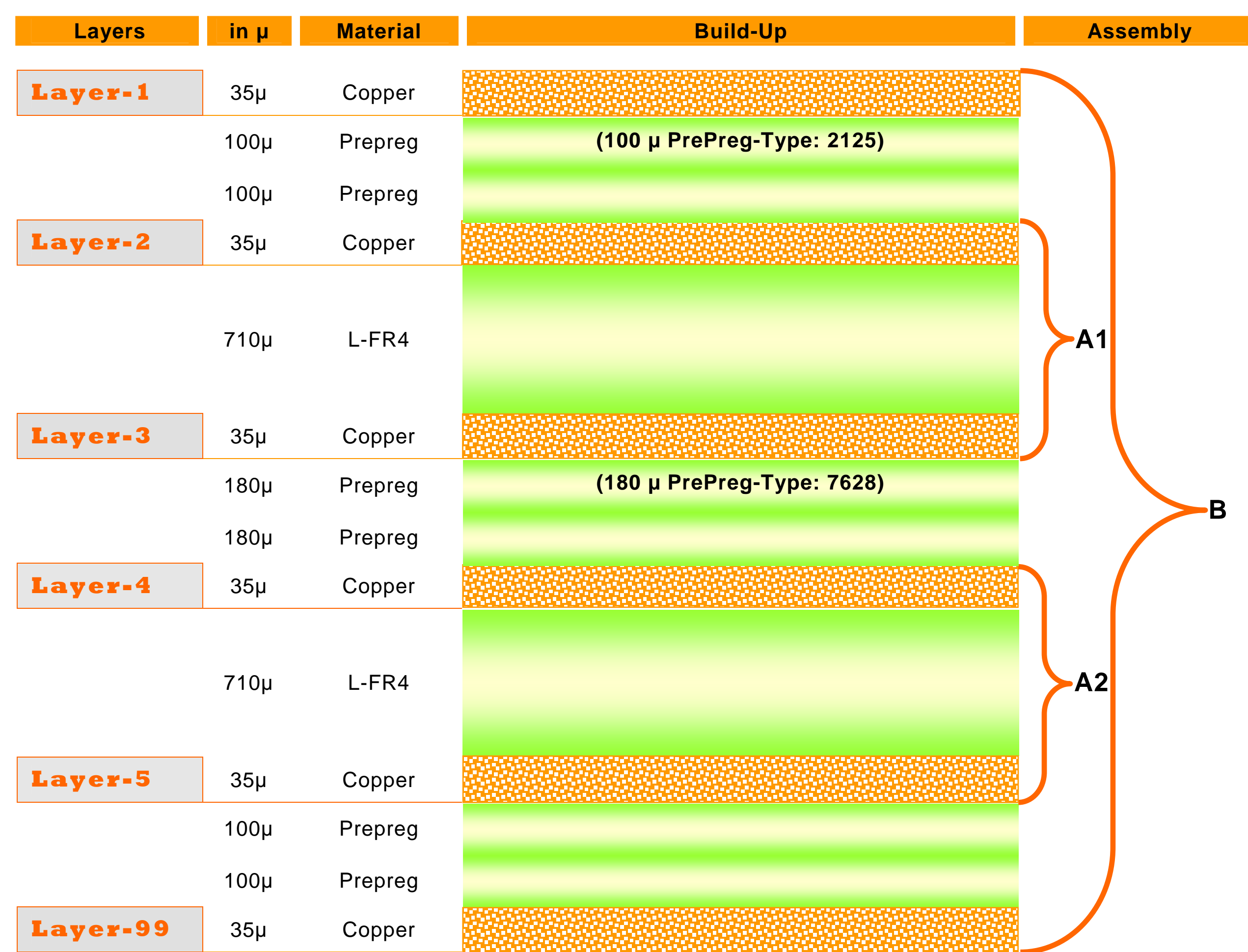
Schematic Key for Multilayer and HDI-Technology Build-Ups



a	b	c	d	e	f	g + h+ i
06	239	FR4	35	L71.35	P18_10	S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_239_FR4_35_L71.35_p18_10_s1



Layers	in µ	Material	Build-Up	Assembly
Layer-1	35µ	Copper		
	100µ	Prepreg	(100 µ PrePreg-Type: 2125)	
	100µ	Prepreg		
Layer-2	35µ	Copper		
	710µ	L-FR4		A1
Layer-3	35µ	Copper		
	180µ	Prepreg	(180 µ PrePreg-Type: 7628)	B
	180µ	Prepreg		
Layer-4	35µ	Copper		
	710µ	L-FR4		A2
Layer-5	35µ	Copper		
	100µ	Prepreg		
	100µ	Prepreg		
Layer-99	35µ	Copper		

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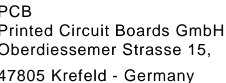

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